

IN-HOUSE TEMPERATURE TEST REPORT

CALIBRATION REPORT NO. – Exd/120919/01	DATE OF CALIBRATION – September 10, 2019
----------------------------------------	------------------------------------------

General, Purpose and Objective:

The main objective is to measure the temperature rise on the Micro-MV enclosure with threaded back & front cover i.e. device under test (DUT) when the instrument is powered with its back & front cover closed condition. Temperature was recorded in the power-on condition through two surface mount chip RTDs at two points A & B. Point “A” is on the outer surface of the enclosure and Point “B” on the module fixed inside the enclosure.

The test was conducted at an ambient environment temperature ~25°C for a duration of 3 hours (until the rise in temperature of both points A & B was not more than 2 k/h).

Items used in this test are as follows,

<u>Ser.#</u>	<u>DESCRIPTION AND IDENTIFICATION OF THE ITEM</u>	<u>Make</u>
1	MICRO-MV FLOW COMPUTER (DUT)	Dynamic Flow Computers
2	KEP Display Unit (To measure and Display Temperature)	KEP
3	PT-100 RTDs (Surface Mount Chip Type)	Detriv
6	DC Power Supply	Scientific

Performed Test and Results in detail:

Abbreviations: Ambient Temperature – Tamb, Inside Enclosure Temperature – Ta, Outer Surface of Enclosure Temperature - Tb

Test Overview:

<u>Ser.#</u>	<u>Test</u>	<u>Parameters</u>
1	Ambient Temperature Operating	<i>Tamb ≈ Ta ≈ Tb = 25°C</i>
2	High Temperature Operating	<i>Ta = 26.5°C , Tb = 25.4°C</i> <i>Duration – 3 h</i>

Test Result:

<u>Ser.#</u>	<u>Time</u>	<u>Temperature</u>
1	14:02	<i>Ta ≈ Tb = 25°C</i>
2	15:07	<i>Ta = 25.1°C , Tb = 25.3°C</i>
3	15:55	<i>Ta = 25.2°C , Tb = 25.8°C</i>
4	16:31	<i>Ta = 25.2°C , Tb = 26.4°C</i>
5	17:07	<i>Ta = 25.2°C , Tb = 26.4°C</i>

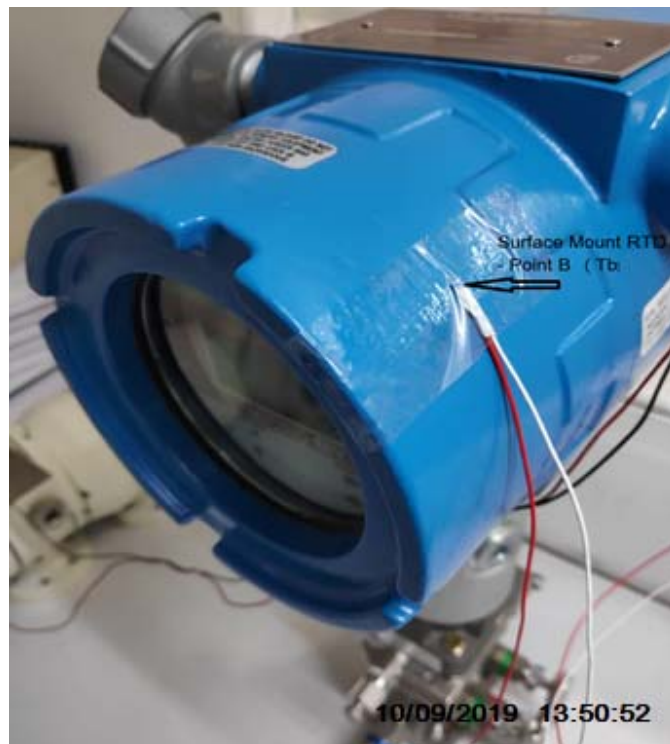
Test Performed By:

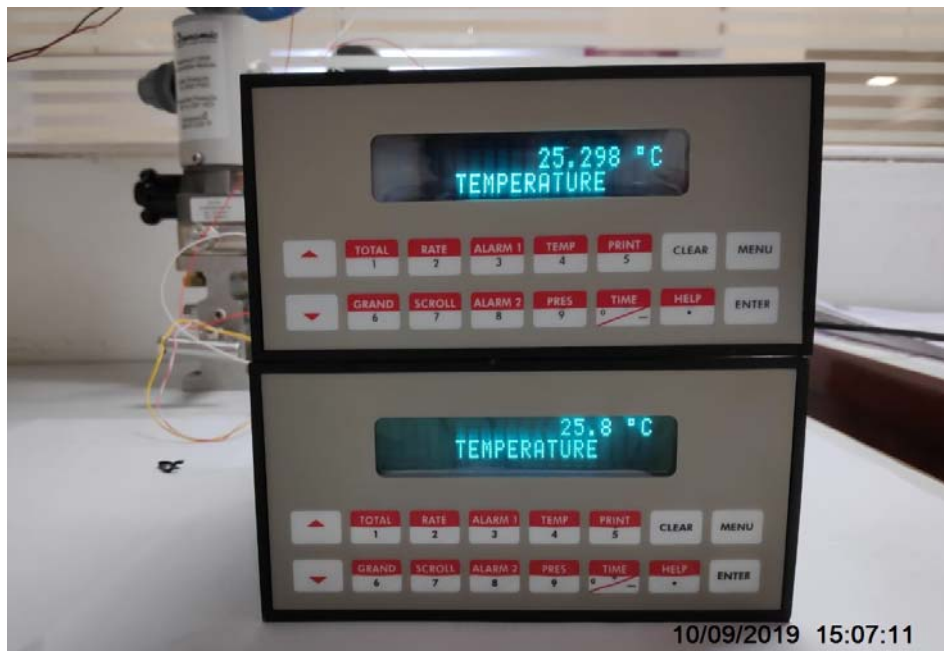
Harish Kumar Singh

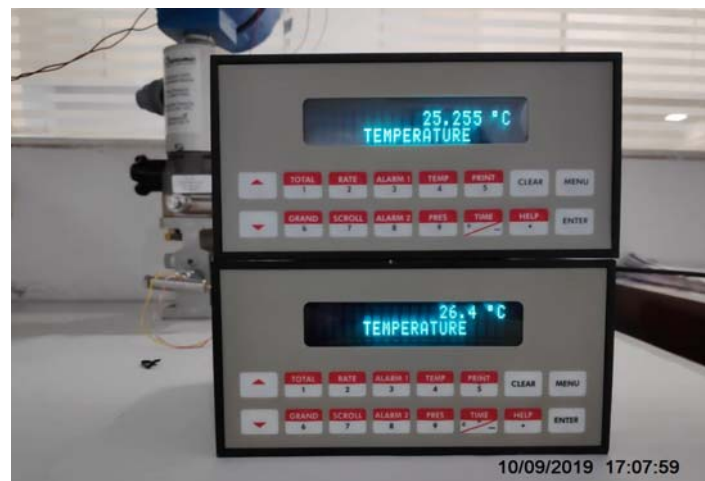
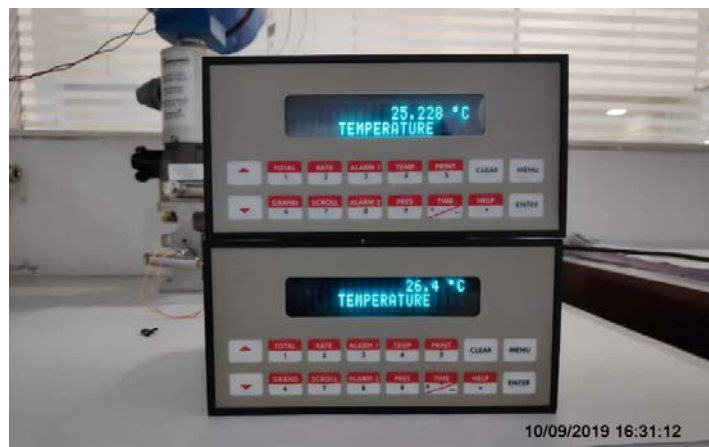
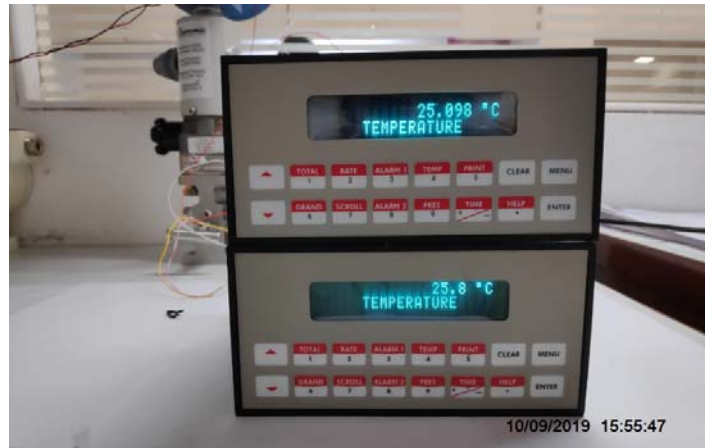
Approved By:

V. Patterson

Test Setup







End of Report